TXS0101 1-Bit Bidirectional Level-Shifting, Voltage-Level Translator With Auto-Direction-Sensing for Open-Drain and Push-Pull Applications

1 Features

- Latch-up performance exceeds 100mA per JESD 78, class II
- ESD protection exceeds JESD 22:
  - A Port:
    - 2500V Human-Body Model (A114-B)
    - 200V Machine Model (A115-A)
    - 1500V Charged-Device Model (C101)
  - B port:
    - 8kV Human-Body Model (A114-B)
    - 200V Machine Model (A115-A)
    - 1500V Charged-Device Model (C101)
- No direction-control signal needed
- Maximum data rates:
  - 24Mbps (push pull)
  - 2Mbps (open drain)
- Available in the Texas Instruments NanoFree™ package
- 1.65V to 3.6V on A port and 2.3V to 5.5V on B port ($V_{CCA} \leq V_{CCB}$)
- V_{CC} isolation feature – if either V_{CC} input is at GND, both ports are in the high-impedance state
- No power-supply sequencing required – either V_{CCA} or V_{CCB} can be ramped first
- I_{off} supports partial-power-down mode operation

2 Applications

- Handsets
- Smartphones
- Tablets
- Desktop PCs

3 Description

This one-bit non-inverting translator uses two separate configurable power-supply rails. The A port is designed to track V_{CCA}. V_{CCA} accepts any supply voltage from 1.65V to 3.6V. V_{CCA} must be less than or equal to V_{CCB} . The B port is designed to track V_{CCB}. V_{CCB} accepts any supply voltage from 2.3V to 5.5V. This allows for low voltage bidirectional translation between any of the 1.8V, 2.5V, 3.3V, and 5V voltage nodes.

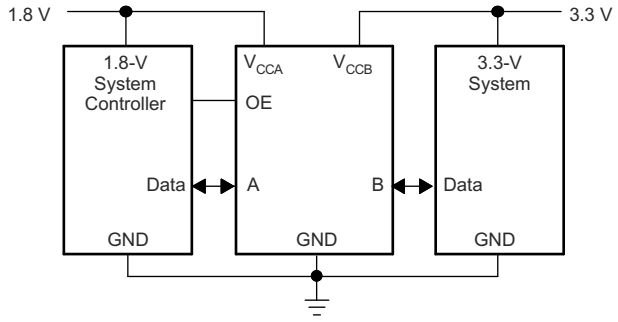
When the output-enable (OE) input is low, all outputs are placed in the high-impedance state.

To put the device in the high-impedance state during power up or power down, tie OE to GND through a pull-down resistor; the current-sourcing capability of the driver determines the minimum value of the resistor.

Package Information

PART NUMBER	PACKAGE (1)	PACKAGE SIZE (2)
TXS0101	DBV (SOT-23, 6)	2.9mm × 2.8mm
	DCK (SC70, 6)	2mm × 2.1mm
	DRL (SOT-5X3, 6)	1.6mm × 1.6mm
	DRY (SON, 6)	1.45mm x 1mm

(1) For more information, see Section 11.
(2) The package size (length × width) is a nominal value and includes pins, where applicable.



Typical Operating Circuit

An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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4 Pin Configuration and Functions

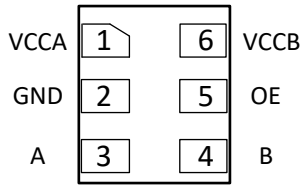

Figure 4-1. DRY Package

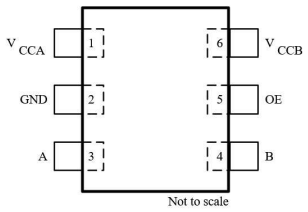

Figure 4-2. DBV, DCK, and DRL Package

Table 4-1. Pin Functions

PIN		TYPE[1]	DESCRIPTION
NAME	DBV, DCK, DRL, DRY		
A	3	I/O	Input/output A. Referenced to V_{CCA}
B	4	I/O	Input/output B. Referenced to V_{CCB}
GND	2	G	Ground
OE	5	I	Output enable. Pull OE low to place all outputs in 3-state mode. Referenced to V_{CCA}.
V_{CCA}	1	I	A-port supply voltage. 1.65V ≤ V_{CCA} ≤ 3.6V and V_{CCA} ≤ V_{CCB}
V_{CCB}	6	I	B-port supply voltage. 2.3V ≤ V_{CCB} ≤ 5.5V

(1) I = input, O = output, G = ground

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5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CCA}	Supply voltage A		–0.5	4.6	V
V_{CCB}	Supply voltage B		–0.5	6.5	V
V_I	Input Voltage(2)	I/O Ports (A Port)	–0.5	4.6	V
V_I	Input Voltage(2)	I/O Ports (B Port), OE	–0.5	6.5	
V_O	Voltage applied to any output in the high-impedance or power-off state(2)	A Port	–0.5	4.6	V
		B Port	–0.5	6.5	
V_O	Voltage applied to any output in the high or low state(2) (3)	A Port	–0.5	V_{CCA} + 0.5	V
		B Port	–0.5	V_{CCB} + 0.5	
I_{IK}	Input clamp current	V_I < 0		–50	mA
I_{OK}	Output clamp current	V_O < 0		–50	mA
I_O	Continuous output current			±50	mA
	Continuous current through V_{CC} or GND			±100	mA
T_j	Junction Temperature			150	°C
T_{stg}	Storage temperature		–65	150	°C

(1) Stresses beyond those listed under Section 5.1 may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Section 5.3 Exposure beyond the limits listed in Section 5.3 may affect device reliability.
(2) The input voltage and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
(3) The output positive-voltage rating may be exceeded up to 6.5 V maximum if the output current rating is observed.

5.2 ESD Ratings

				VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	A Port	±2500	V
			B Port	±8000	
		Charged device model (CDM), per ANSI/ESDA/JEDEC JS-002(2)	B Port	±1500	
			A Port	±200	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted) (1) (2) (3)

			V_{CCA}	V_{CCB}	MIN	MAX	UNIT
V_{CCA}	Supply voltage A				1.65	3.6	V
V_{CCB}	Supply voltage B				2.3	5.5	V
V_{IH}	High-level input voltage	A-port I/O's	1.65 V to 1.95 V	2.3 V to 5.5 V	V_{CCI} - 0.2	V_{CCI}	V
			2.3 V to 3.6 V		V_{CCI} - 0.4	V_{CCI}	
		B-port I/O's	1.65 V to 3.6 V	2.3 V to 5.5 V	V_{CCI} - 0.4	V_{CCI}	
		OE Input			V_{CCA} x 0.65	5.5	
V_{IL}	Low-level input voltage	A-port I/O's	1.65 V to 3.6 V	2.3 V to 5.5 V	0	0.15	V
		B-port I/O's			0	0.15	
		OE Input			0	V_{CCA} x 0.35	
Δt/Δv	Input transition rise and fall time	A//B Port I/Os, Push-Pull Driving	1.65 V to 3.6 V	2.3 V to 5.5 V		10	ns/V
T_A	Operating free-air temperature				–40	85	°C

(1) V_{CCI} is the V_{CC} associated with the input port.
(2) V_{CCO} is the V_{CC} associated with the output port.
(3) All control inputs and data I/Os of this device have weak pulldowns to ensure the line is not floating when undefined external to the device. The input leakage from these weak pulldowns is defined by the I_I specification indicated under Section 5.5

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5.4 Thermal Information

THERMAL METRIC[1]		TXS0101				UNIT
		DCK	DRY	DRL	DBV	
		6 PINS	6 PINS	6 PINS	6 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	222.9	277.6	207.5	195.3	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	157.0	163.1	108.9	114.5	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	77.4	158.9	88.5	76.0	°C/W
Y_{JT}	Junction-to-top characterization parameter	58.6	29.3	6.3	51.7	°C/W
Y_{JB}	Junction-to-board characterization parameter	77.1	158.2	88.1	75.7	°C/W
$R_{\theta JC(bottom)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	N/A	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

5.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)[1] [2]

PARAMETER		TEST CONDITIONS	V_{CCA}	V_{CCB}	Operating free-air temperature (T_A)			UNIT
					–40°C to 85°C			
					MIN	TYP	MAX	
V_{OHA}	Port A output high voltage [3]	I_{OH} = –20 uA, $V_{IB} \geq V_{CCB}$ - 0.4 V	1.65 V to 3.6 V	2.3 V to 5.5 V	V_{CCA} x 0.67			V
V_{OLA}	Port A output low voltage [4]	I_{OL} = 1 mA, $V_{IB} \leq$ 0.15 V	1.65 V to 3.6 V	2.3 V to 5.5 V			0.4	V
V_{OHB}	Port B output high voltage	I_{OH} = –20 uA, $V_{IA} \geq V_{CCA}$ - 0.2 V	1.65 V to 3.6 V	2.3 V to 5.5 V	V_{CCB} x 0.67			V
V_{OLB}	Port B output low voltage [4]	I_{OL} = 1 mA, $V_{IA} \leq$ 0.15 V	1.65 V to 3.6 V	1.65 V to 5.5 V			0.4	V
I_I	Input leakage current	OE $V_I = V_{CC}$ or GND, T_A= 25°C	1.65 V to 3.6 V	1.65 V to 5.5 V	-1		1	µA
I_I	Input leakage current	OE $V_I = V_{CC}$ or GND, -40°C- 85°C	1.65 V to 3.6 V	1.65 V to 5.5 V	-2		2	µA
I_{off}	Partial power down current	A port	0 V	0 V to 5.5 V	-2		2	µA
		B port	0 V to 3.6 V	0 V	-2		2	µA
I_{OZ}	Tri-state output current	A or B Port: $V_I = V_{CCI}$ or GND $V_O = V_{CCO}$ or GND OE = GND	1.65 V to 3.6 V	2.3 V to 5.5 V	–2		2	µA
I_{CCA}	V_{CCA} supply current	$V_I = V_{CCI}$ or GND I_O = 0	1.65 V to V_{CCB}	2.3 V to 5.5 V			2.4	µA
			3.6 V	0 V			2.2	
			0 V	5.5 V			-1	
I_{CCB}	V_{CCB} supply current	$V_I = V_{CCI}$ or GND I_O = 0	1.65 V to V_{CCB}	2.3 V to 5.5 V			12	µA
			3.6 V	0 V			-1	
			0 V	5.5 V			1	
I_{CCA} + I_{CCB}	Combined supply current	$V_I = V_{CCI}$ or GND I_O = 0	1.65 V to V_{CCB}	2.3 V to 5.5 V			14.4	µA
C_i	Input Capacitance	OE	3.3 V	3.3 V			3.5	pF
C_{io}	A port	T_A= 25°C	3.3 V	3.3 V		5		pF
		-40°C - 85°C			6			
C_{io}	B port	T_A= 25°C	3.3 V	3.3 V		6		pF
		-40°C - 85°C			7.5			

(1) V_{CCI} is the V_{CC} associated with the input port
(2) V_{CCO} is the V_{CC} associated with the output port
(3) Tested at $V_I = V_{T+(MAX)}$

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(4) Tested at $V_I = V_{T-(MIN)}$

5.6 Switching Characteristics, V_{CCA} = 1.8 ± 0.15 V

PARAMETER		FROM	TO	Test Conditions	B-Port Supply Voltage (V_{CCB})									UNIT
					2.5 ± 0.2 V			3.3 ± 0.3 V			5.0 ± 0.5 V			
					MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
t_{PHL}	Propagation Delay (Hight-to-Low)	A	B	Push-Pull			5.3			5.4			6.8	ns
				Open-Drain	2.3		8.8	2.4		9.6	2.6		10	
t_{PLH}	Propagation Delay (Low-to-High)	A	B	Push-Pull			6.8			7.1			7.5	ns
				Open-Drain	45		260	36		208	27		198	
t_{PHL}	Propagation Delay (Hight-to-Low)	B	A	Push-Pull			4.4			4.5			4.7	ns
				Open-Drain	1.9		5.3	1.1		4.4	1.2		4	
t_{PLH}	Propagation Delay (Low-to-High)	B	A	Push-Pull			5.3			4.5			0.5	ns
				Open-Drain	45		175	36		140	27		102	
t_{en}	Enable Time	OE	A or B	Push-Pull			200			200			200	ns
t_{dis}	Disable Time						50			40			35	
t_{rA}	Ouput Rise Time	B	A	Push-Pull	3.2		9.5	2.3		9.3	2		7.6	ns
				Open-Drain	38		165	30		132	22		95	
t_{rB}	Ouput Rise Time	A	B	Push-Pull	1.1		10.8	1		9.1	1		7.6	ns
				Open-Drain	34		145	23		106	10		76	
t_{fA}	Output Fall Time	B	A	Push-Pull	1.9		5.9	1.9		6	1.4		13.3	ns
				Open-Drain	4.4		6.9	4.3		6.4	4.2		6.1	
t_{fB}	Output Fall Time	A	B	Push-Pull	2.2		13.8	2.2		16.2	2.6		16.2	ns
				Open-Drain	6.9		13.8	7.5		16.2	7		16.2	

5.7 Switching Characteristics, V_{CCA} = 2.5 ± 0.2 V

PARAMETER		FROM	TO	Test Conditions	B-Port Supply Voltage (V_{CCB})									UNIT
					2.5 ± 0.2 V			3.3 ± 0.3 V			5.0 ± 0.5 V			
					MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
t_{PHL}	Propagation Delay (Hight-to-Low)	A	B	Push-Pull			3.2			3.7			3.8	ns
				Open-Drain	1.7		6.3	2		6	2.1		5.8	
t_{PLH}	Propagation Delay (Low-to-High)	A	B	Push-Pull			3.5			4.1			4.4	ns
				Open-Drain	43		250	36		206	27		190	
t_{PHL}	Propagation Delay (Hight-to-Low)	B	A	Push-Pull			3			3.6			4.3	ns
				Open-Drain	1.8		4.7	1.6		4.2	1.2		4	
t_{PLH}	Propagation Delay (Low-to-High)	B	A	Push-Pull			2.5			1.6			1	ns
				Open-Drain	44		170	37		140	27		103	
t_{en}	Enable Time	OE	A or B	Push-Pull			200			200			200	ns
t_{dis}	Disable Time						50			40			35	
t_{rA}	Ouput Rise Time	B	A	Push-Pull	2.8		7.4	2.1		6.6	0.9		5.6	ns
				Open-Drain	34		149	28		121	24		89	
t_{rB}	Ouput Rise Time	A	B	Push-Pull	1.3		8.3	0.9		7.2	0.4		6.1	ns
				Open-Drain	35		151	24		112	12		81	
t_{fA}	Output Fall Time	B	A	Push-Pull	1.9		5.7	1.4		5.5	0.8		5.3	ns
				Open-Drain	4.4		6.9	4.3		6.2	4.2		5.8	
t_{fB}	Output Fall Time	A	B	Push-Pull	2.2		7.8	2.4		6.7	2.6		6.6	ns
				Open-Drain	5.1		8.8	5.4		9.4	5.4		10.4	

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5.8 Switching Characteristics, V_{CCA} = 3.3 ± 0.3 V

PARAMETER		FROM	TO	Test Conditions	B-Port Supply Voltage (V_{CCB})						UNIT
					3.3 ± 0.3 V			5.0 ± 0.5 V			
					MIN	TYP	MAX	MIN	TYP	MAX	
t_{PHL}	Propagation Delay (Hight-to-Low)	A	B	Push-Pull			2.4			3.1	ns
				Open-Drain	1.3		4.2	1.4		4.6	
t_{PLH}	Propagation Delay (Low-to-High)	A	B	Push-Pull			4.2			4.4	ns
				Open-Drain	36		204	28		165	
t_{PHL}	Propagation Delay (Hight-to-Low)	B	A	Push-Pull			2.5			3.3	ns
				Open-Drain	1		124	1		97	
t_{PLH}	Propagation Delay (Low-to-High)	B	A	Push-Pull			2.5			2.6	ns
				Open-Drain	3		139	3		105	
t_{en}	Enable Time	OE	A or B	Push-Pull			200			200	ns
t_{dis}	Disable Time						40			9.8	
t_{rA}	Ouput Rise Time	B	A	Push-Pull	2.3		5.6	1.9		4.8	ns
				Open-Drain	25		116	19		85	
t_{rB}	Ouput Rise Time	A	B	Push-Pull	1.6		6.4	0.6		7.4	ns
				Open-Drain	26		116	14		72	
t_{fA}	Output Fall Time	B	A	Push-Pull	1.4		5.4	1		5	ns
				Open-Drain	4.3		6.1	4.2		5.7	
t_{fB}	Output Fall Time	A	B	Push-Pull	2.3		7.4	2.4		7.6	ns
				Open-Drain	5		7.6	4.8		8.3	

5.9 Switching Characteristics: T_{sk}, T_{MAX}

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CCA}	V_{CCB}	Operating free-air temperature (T_A)			UNIT
					-40°C to 125°C			
					MIN	TYP	MAX	
T_{MAX} - Maximum Data Rate	50% Duty Cycle Input One channel switching	Push-Pull Driving	1.8 ± 0.15 V	2.5 V ± 0.2 V	21			Mbps
				3.3 V ± 0.3 V	22			
				5 V ± 0.5 V	24			
			2.5 V ± 0.2 V	2.5 V ± 0.2 V	20			
				3.3 V ± 0.3 V	22			
				5 V ± 0.5 V	24			
			3.3 V ± 0.3 V	3.3 V ± 0.3 V	23			
				5 V ± 0.5 V	24			
		Open-Drain Driving	1.8 ± 0.15 V	2.5 V ± 0.2 V	2			
				3.3 V ± 0.3 V	2			
				5 V ± 0.5 V	2			
			2.5 V ± 0.2 V	2.5 V ± 0.2 V	2			
				3.3 V ± 0.3 V	2			
				5 V ± 0.5 V	1			
			3.3 V ± 0.3 V	3.3 V ± 0.3 V	2			
				5 V ± 0.5 V	2			
t_w	Pulse Duration, Data Inputs	Push-Pull Driving	1.8 V ± 0.15 V to 3.3 V ± 0.3 V	2.5 V ± 0.2 V to 5.5 V ± 0.5 V	41			ns
		Open-Drain Driving	1.8 V ± 0.15 V to 3.3 V ± 0.3 V	2.5 V ± 0.2 V to 5.5 V ± 0.5 V	500			

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5.10 Typical Characteristics

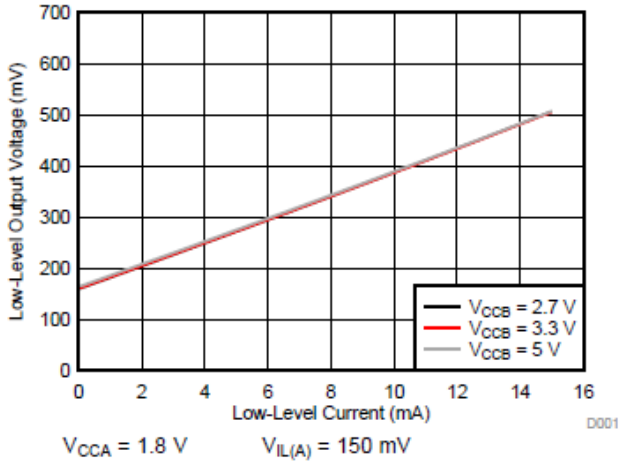

Figure 5-1. Low-Level Output Voltage ($V_{OL(Bx)}$) vs Low-Level Current ($I_{OL(Bx)}$)

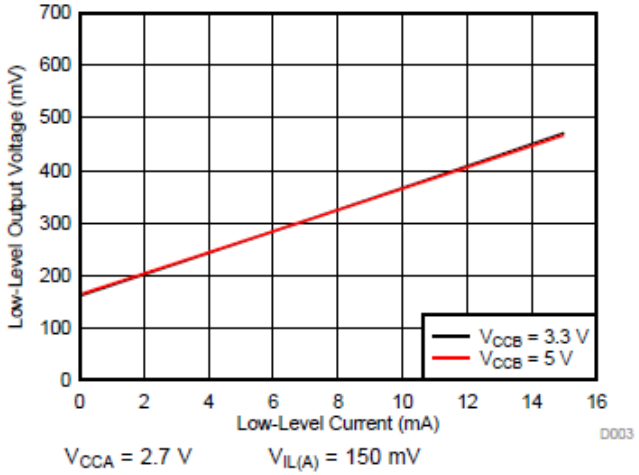

Figure 5-2. Low-Level Output Voltage ($V_{OL(Bx)}$) vs Low-Level Current ($I_{OL(Bx)}$)

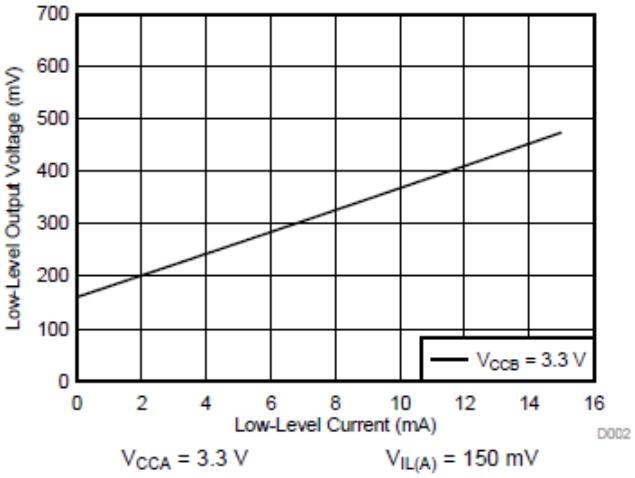

Figure 5-3. Low-Level Output Voltage ($V_{OL(Bx)}$) vs Low-Level Current ($I_{OL(Bx)}$)

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6 Parameter Measurement Information

6.1 Load Circuits

Figure 6-1 shows the push-pull driver circuit used for measuring data rate, pulse duration, propagation delay, output rise-time and fall-time. Figure 6-2 shows the open-drain driver circuit used for measuring data rate, pulse duration, propagation delay, output rise-time and fall-time.

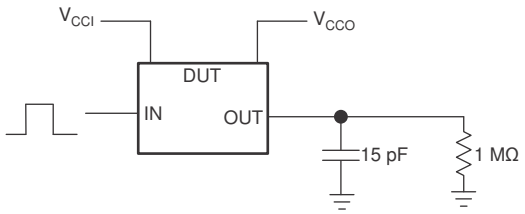

Figure 6-1. Data Rate, Pulse Duration, Propagation Delay, Output Rise-Time and Fall-Time Measurement Using a Push-Pull Driver

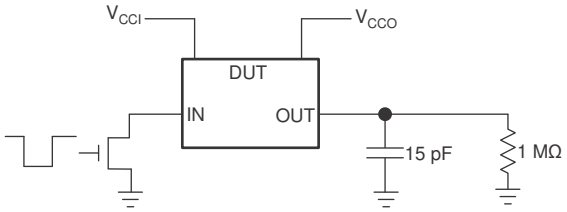

Figure 6-2. Data Rate, Pulse Duration, Propagation Delay, Output Rise-Time and Fall-Time Measurement Using an Open-Drain Driver

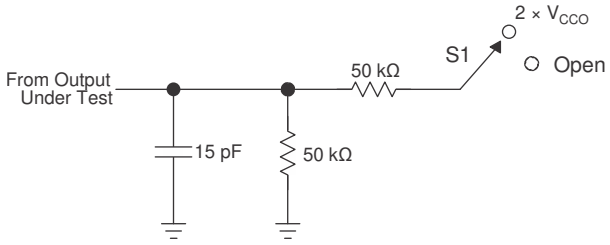

Figure 6-3. Load Circuit for Enable-Time and Disable-Time Measurement

TEST	S1
t_{PZL} / t_{PLZ} (t_{dis})	2 × V_{CCO}
t_{PHZ} / t_{PZH} (t_{en})	Open

1. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
2. t_{PZL} and t_{PZH} are the same as t_{en}.
3. V_{CCI} is the V_{CC} associated with the input port.
4. V_{CCO} is the V_{CC} associated with the output port.

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6.2 Voltage Waveforms

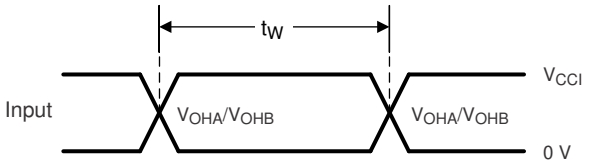


Figure 6-4. Pulse Duration (Push-Pull)

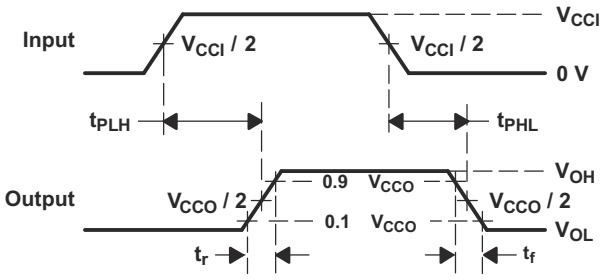
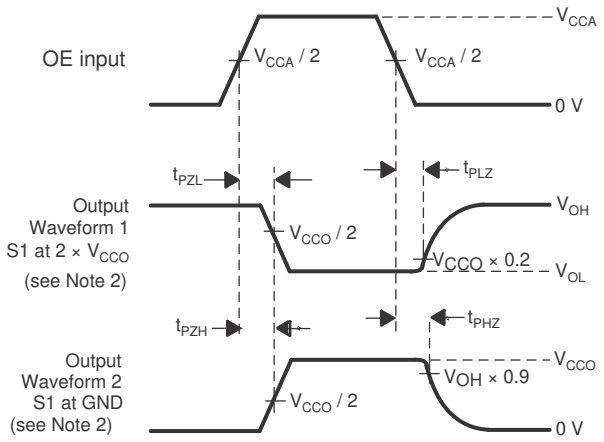


Figure 6-5. Propagation Delay Times



- C_L includes probe and jig capacitance.
- Waveform 1 in Figure 6-6 is for an output with internal such that the output is high, except when OE is high (see Figure 6-3). Waveform 2 in Figure 6-6 is for an output with conditions such that the output is low, except when OE is high.
- All input pulses are supplied by generators having the following characteristics: PRR ≤ 10MHz, Z_O = 50Ω, dv/dt ≥ 1V/ns.
- The outputs are measured one at a time, with one transition per measurement.
- t_{PLZ} and t_{PHZ} are the same as t_{dis}.
- t_{PZL} and t_{PZH} are the same as t_{en}.
- t_{PLH} and t_{PHL} are the same as t_{pd}.
- V_{CCI} is the V_{CC} associated with the input port.
- V_{CCO} is the V_{CC} associated with the output port.

Figure 6-6. Enable and Disable Times

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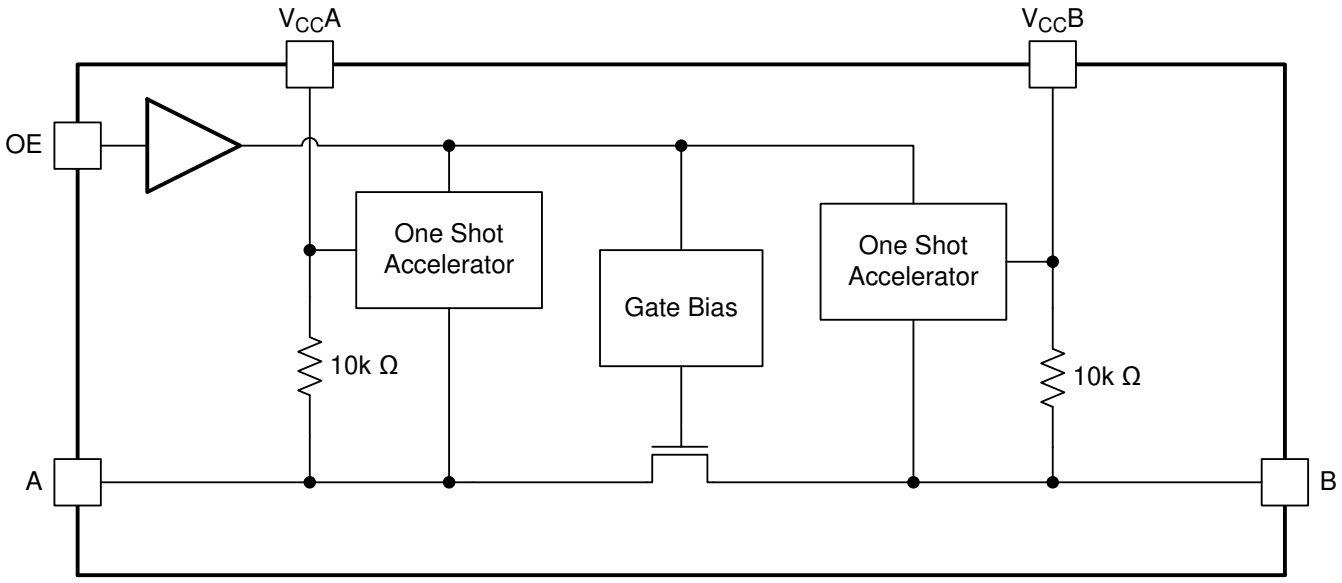
7 Detailed Description

7.1 Overview

The TXS0101 device is a directionless voltage-level translator specifically designed for translating logic voltage levels. The A port can accept I/O voltages ranging from 1.65V to 3.6V, while the B port can accept I/O voltages from 2.3V to 5.5V. The device is a pass gate architecture with edge rate accelerators (one shots) to improve the overall data rate. 10kΩ pullup resistors, commonly used in open drain applications, have been conveniently integrated so that an external resistor is not needed. While this device is designed for open drain applications, the device can also translate push-pull CMOS logic outputs.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Architecture

As shown in Figure 7-1, the TXS0101 architecture does not require a direction-control signal to control the direction of data flow from A to B or from B to A.

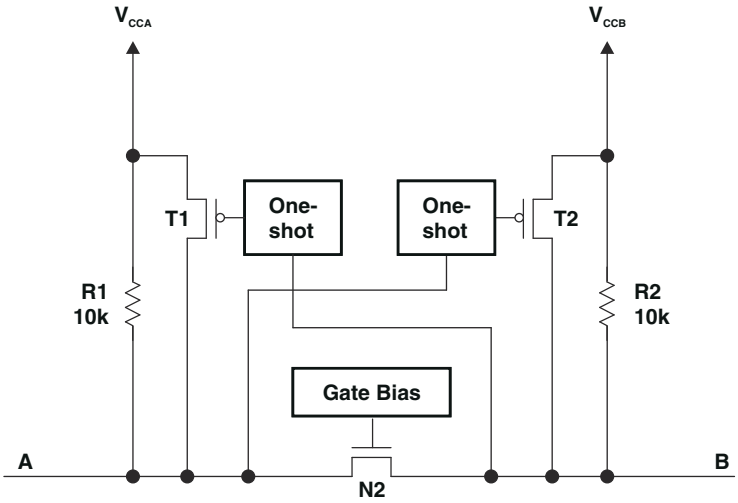


Figure 7-1. Architecture of a TXS01xx Cell

Each A-port I/O has an internal 10kΩ pullup resistor to V_{CCA}, and each B-port I/O has an internal 10kΩ pullup resistor to V_{CCB}. The output one-shots detect rising edges on the A or B ports. During a rising edge, the one-shot turns on the PMOS transistors (T1 and T2) for a short duration, which speeds up the low-to-high transition.

7.3.2 Input Driver Requirements

The fall time (t_{fA} and t_{fB}) of a signal depends on the output impedance of the external device driving the data I/Os of the TXS0101. Similarly, the t_{PHL} and maximum data rates also depend on the output impedance of the external driver. The values for t_{fA}, t_{fB}, t_{PHL}, and maximum data rates in the data sheet assume that the output impedance of the external driver is less than 50Ω.

7.3.3 Power Up

During operation, ensure that $V_{CCA} \leq V_{CCB}$ at all times. During power-up sequencing, $V_{CCA} \geq V_{CCB}$ does not damage the device, so any power supply can be ramped up first.

7.3.4 Enable and Disable

The TXS0101 has an OE input that is used to disable the device by setting OE low, which places all I/Os in the Hi-Z state. The disable time (t_{dis}) indicates the delay between the time when OE goes low and when the outputs actually get disabled (Hi-Z). The enable time (t_{en}) indicates the amount of time the user must allow for the one-shot circuitry to become operational after OE is taken high.

7.3.5 Pullup or Pulldown Resistors on I/O Lines

Each A-port I/O has an internal 10kΩ pullup resistor to V_{CCA}, and each B-port I/O has an internal 10kΩ pullup resistor to V_{CCB}. If a smaller value of pullup resistor is required, an external resistor must be added from the I/O to V_{CCA} or V_{CCB} (in parallel with the internal 10kΩ resistors).

7.4 Device Functional Modes

The TXS0101 device has two functional modes, enabled and disabled. To disable the device set the OE input low, which places all I/Os in a high impedance state. Setting the OE input high will enable the device.

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8 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

8.1 Application Information

The TXS0101 can be used in level-translation applications for interfacing devices or systems operating at different interface voltages with one another. The TXS0101 is an excellent choice for use in applications where an open-drain driver is connected to the data I/Os. The TXS0101 can also be used in applications where a push-pull driver is connected to the data I/Os, but the TXB0102 might be a better option for such push-pull applications.

8.2 Typical Application

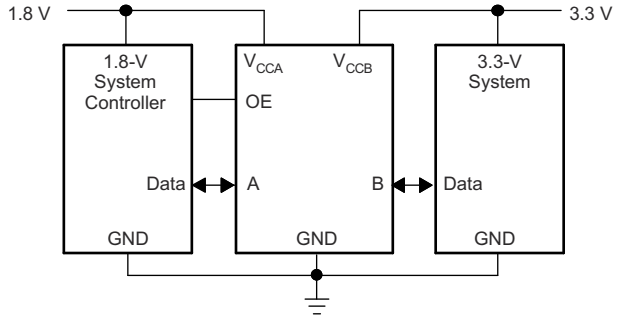

Figure 8-1. Typical Application Schematic

8.2.1 Design Requirements

For this design example, use the parameters listed in Table 8-1.

Table 8-1. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
Input voltage range	1.65 to 3.6V
Output voltage range	2.3 to 5.5V

8.2.2 Detailed Design Procedure

To begin the design process, determine the following:

- Input voltage range:
  - Use the supply voltage of the device that is driving the TXS0101 device to determine the input voltage range. For a valid logic high the value must exceed the V_{IH} of the input port. For a valid logic low the value must be less than the V_{IL} of the input port.
- Output voltage range:
  - Use the supply voltage of the device that the TXS0101 device is driving to determine the output voltage range.
  - The TXS0101 device has 10kΩ internal pullup resistors. External pullup resistors can be added to reduce the total RC of a signal trace if necessary.

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- An external pull down resistor decreases the output V_{OH} and V_{OL}. Use Equation 1 to calculate the V_{OH} as a result of an external pull down resistor.

$$V_{OH} = V_{CCx} \times R_{PD} / (R_{PD} + 10k\Omega) \quad (1)$$

where

- V_{CCx} is the supply voltage on either V_{CCA} or V_{CCB}
- R_{PD} is the value of the external pull down resistor

8.2.3 Application Curve

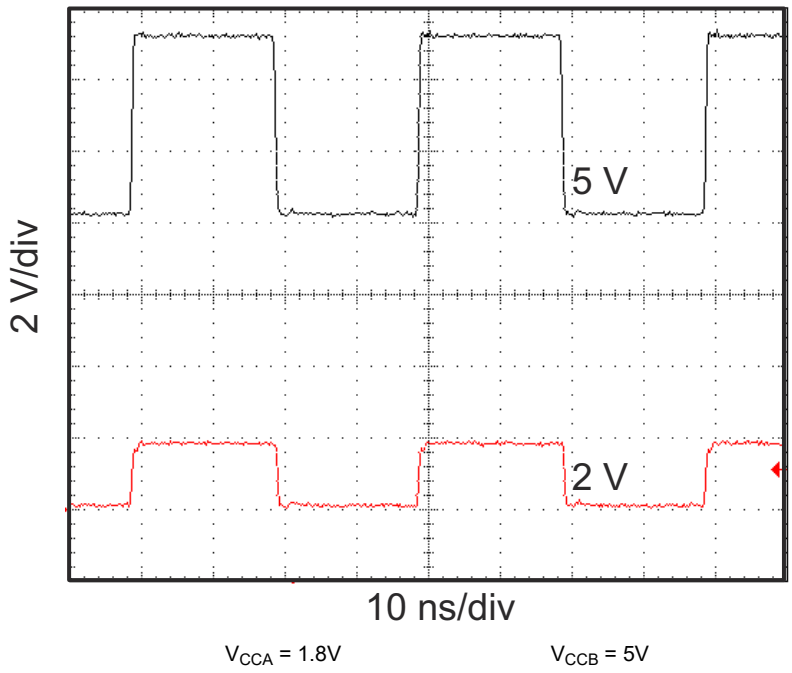

Figure 8-2. Level-Translation of a 2.5MHz Signal

8.3 Power Supply Recommendations

The TXS0101 device uses two separate configurable power-supply rails, V_{CCA} and V_{CCB}. V_{CCB} accepts any supply voltage from 2.3V to 5.5V and V_{CCA} accepts any supply voltage from 1.65V to 3.6V. The A port and B port are designed to track V_{CCA} and V_{CCB} respectively allowing for low voltage bidirectional translation between any of the 1.8V, 2.5V, 3.3V, and 5V voltage nodes.

The TXS0101 device does not require power sequencing between V_{CCA} and V_{CCB} during power-up so the powersupply rails can be ramped in any order. A V_{CCA} value greater than or equal to V_{CCB} ($V_{CCA} \geq V_{CCB}$) does not damage the device, but during operation, V_{CCA} must be less than or equal to V_{CCB} ($V_{CCA} \leq V_{CCB}$) at all times.

The output-enable (OE) input circuit is designed so that it is supplied by V_{CCA} and when the (OE) input is low, all outputs are placed in the high-impedance state. To put the outputs in the high-impedance state during power up or power down, the OE input pin must be tied to GND through a pulldown resistor and must not be enabled until V_{CCA} and V_{CCB} are fully ramped and stable. The current-sourcing capability of the driver determines the minimum value of the pulldown resistor to ground.

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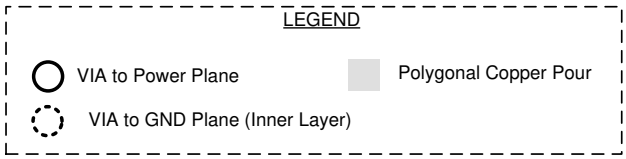
8.4 Layout

8.4.1 Layout Guidelines

For device reliability, TI recommends following common printed-circuit board layout guidelines such as follows:

- Bypass capacitors should be used on power supplies.
- Short trace lengths should be used to avoid excessive loading.
- PCB signal trace-lengths must be kept short enough so that the round-trip delay of any reflection is less than the one shot duration, approximately 30ns, causing any reflection to encounter low impedance at the source driver.
- Placing pads on the signal paths for loading capacitors or pullup resistors to help adjust rise and fall times of signals depending on the system requirements

8.4.2 Layout Example



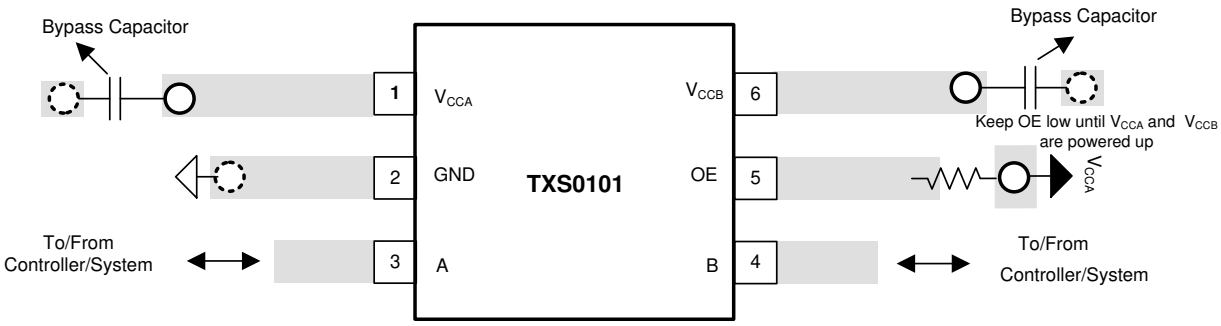


Figure 8-3. Typical Layout of TXS0101

9 Device and Documentation Support

9.1 Device Support

9.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, *A Guide to Voltage Translation With TXS-Type Translators*
- Texas Instruments, *Introduction to Logic*

9.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

9.3 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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9.4 Trademarks

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9.5 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

9.6 Glossary

TI Glossary	This glossary lists and explains terms, acronyms, and definitions.

10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision D (June 2017) to Revision E (October 2024)	Page
• Added DRY pinout diagram	3

Changes from Revision C (December 2015) to Revision D (June 2017)	Page
• Changed YZP package pinout diagram with new image and added YZP pin assignments in *Pin Functions* table	3

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TXS0101DBVR	ACTIVE	SOT-23	DBV	6	3000	RoHS & Green	Call TI | NIPDAU	Level-1-260C-UNLIM	-40 to 85	(35WH, NFFF, NFFR)	Samples
TXS0101DBVRG4	ACTIVE	SOT-23	DBV	6	3000	RoHS & Green	Call TI	Level-1-260C-UNLIM	-40 to 85	(35WH, NFFF, NFFR)	Samples
TXS0101DBVT	ACTIVE	SOT-23	DBV	6	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	NFFR	Samples
TXS0101DCKR	ACTIVE	SC70	DCK	6	3000	RoHS & Green	Call TI | SN | NIPDAU	Level-1-260C-UNLIM	-40 to 85	(1PR, 2GO)	Samples
TXS0101DCKT	ACTIVE	SC70	DCK	6	250	RoHS & Green	Call TI | NIPDAU	Level-1-260C-UNLIM	-40 to 85	(1PR, 2GO)	Samples
TXS0101DRLR	ACTIVE	SOT-5X3	DRL	6	4000	RoHS & Green	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	2GR	Samples
TXS0101YZPR	ACTIVE	DSBGA	YZP	6	3000	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 85	2GN	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TXS0101 :

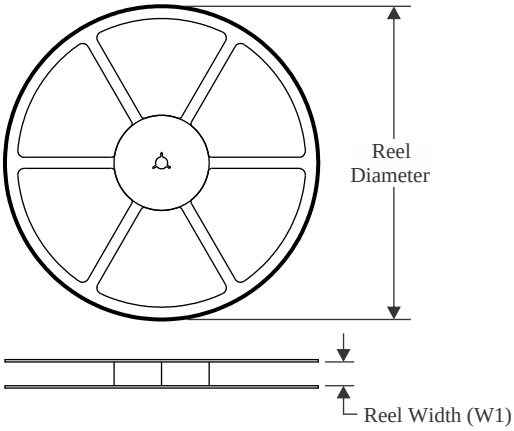
- Automotive : TXS0101-Q1

NOTE: Qualified Version Definitions:

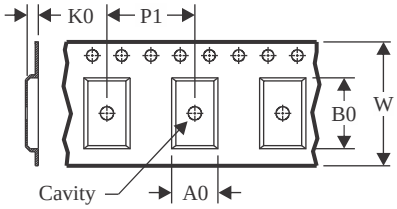
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

REEL DIMENSIONS

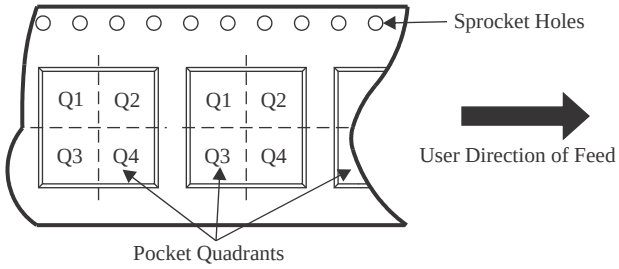


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

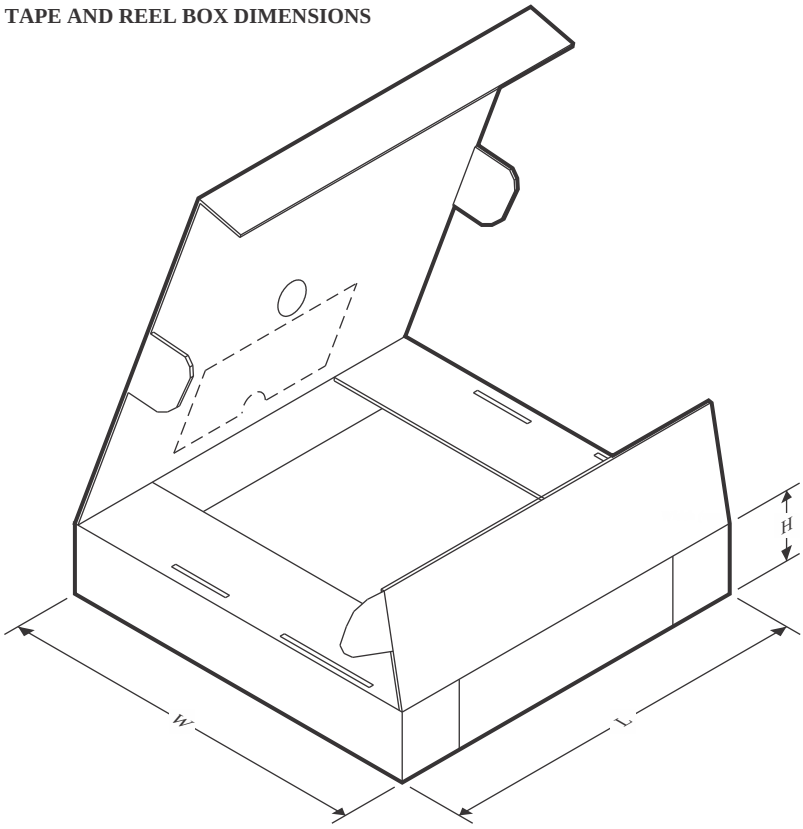
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TXS0101DBVR	SOT-23	DBV	6	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
TXS0101DBVT	SOT-23	DBV	6	250	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
TXS0101DCKR	SC70	DCK	6	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TXS0101DCKR	SC70	DCK	6	3000	180.0	8.4	2.3	2.5	1.2	4.0	8.0	Q3
TXS0101DCKT	SC70	DCK	6	250	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TXS0101DRLR	SOT-5X3	DRL	6	4000	180.0	8.4	1.98	1.78	0.69	4.0	8.0	Q3
TXS0101YZPR	DSBGA	YZP	6	3000	178.0	9.2	1.02	1.52	0.63	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

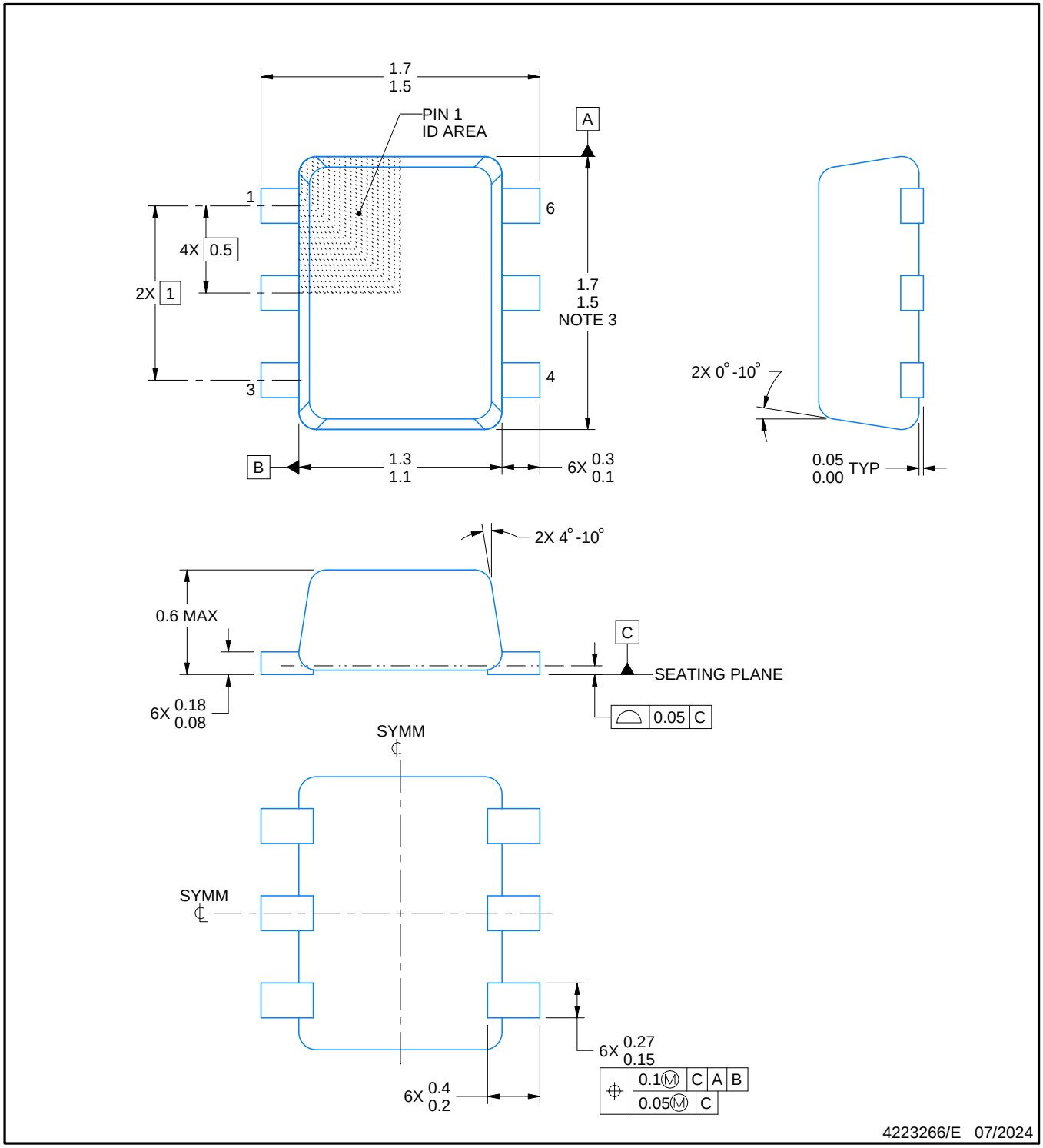
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TXS0101DBVR	SOT-23	DBV	6	3000	202.0	201.0	28.0
TXS0101DBVT	SOT-23	DBV	6	250	202.0	201.0	28.0
TXS0101DCKR	SC70	DCK	6	3000	200.0	183.0	25.0
TXS0101DCKR	SC70	DCK	6	3000	210.0	185.0	35.0
TXS0101DCKT	SC70	DCK	6	250	200.0	183.0	25.0
TXS0101DRLR	SOT-5X3	DRL	6	4000	202.0	201.0	28.0
TXS0101YZPR	DSBGA	YZP	6	3000	220.0	220.0	35.0

PACKAGE OUTLINE

DRL0006A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



NOTES:

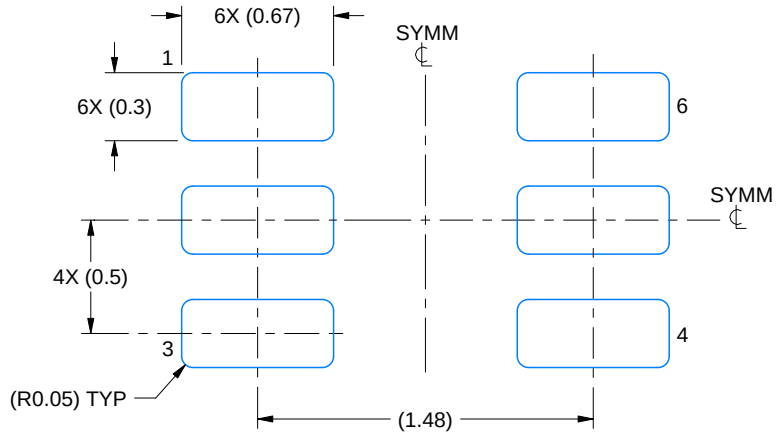
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-293 Variation UAAD

EXAMPLE BOARD LAYOUT

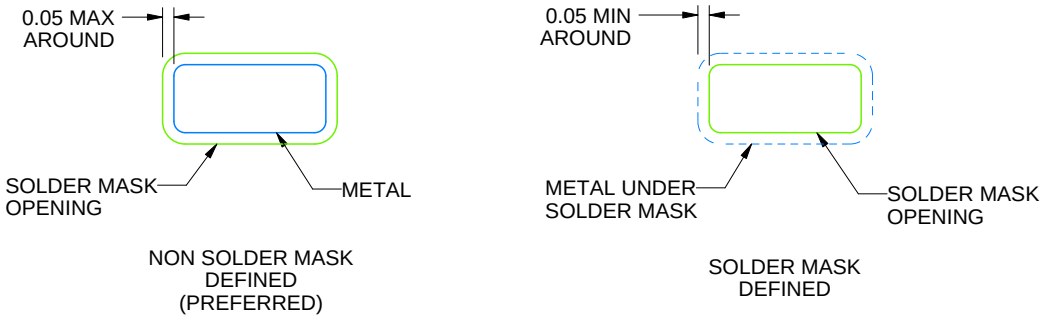
DRL0006A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE
SCALE:30X

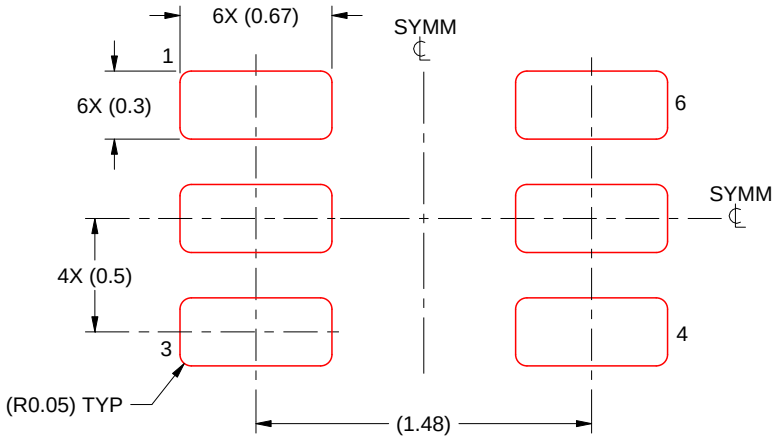


SOLDERMASK DETAILS

4223266/E 07/2024

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
7. Land pattern design aligns to IPC-610, Bottom Termination Component (BTC) solder joint inspection criteria.



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:30X

4223266/E 07/2024

NOTES: (continued)

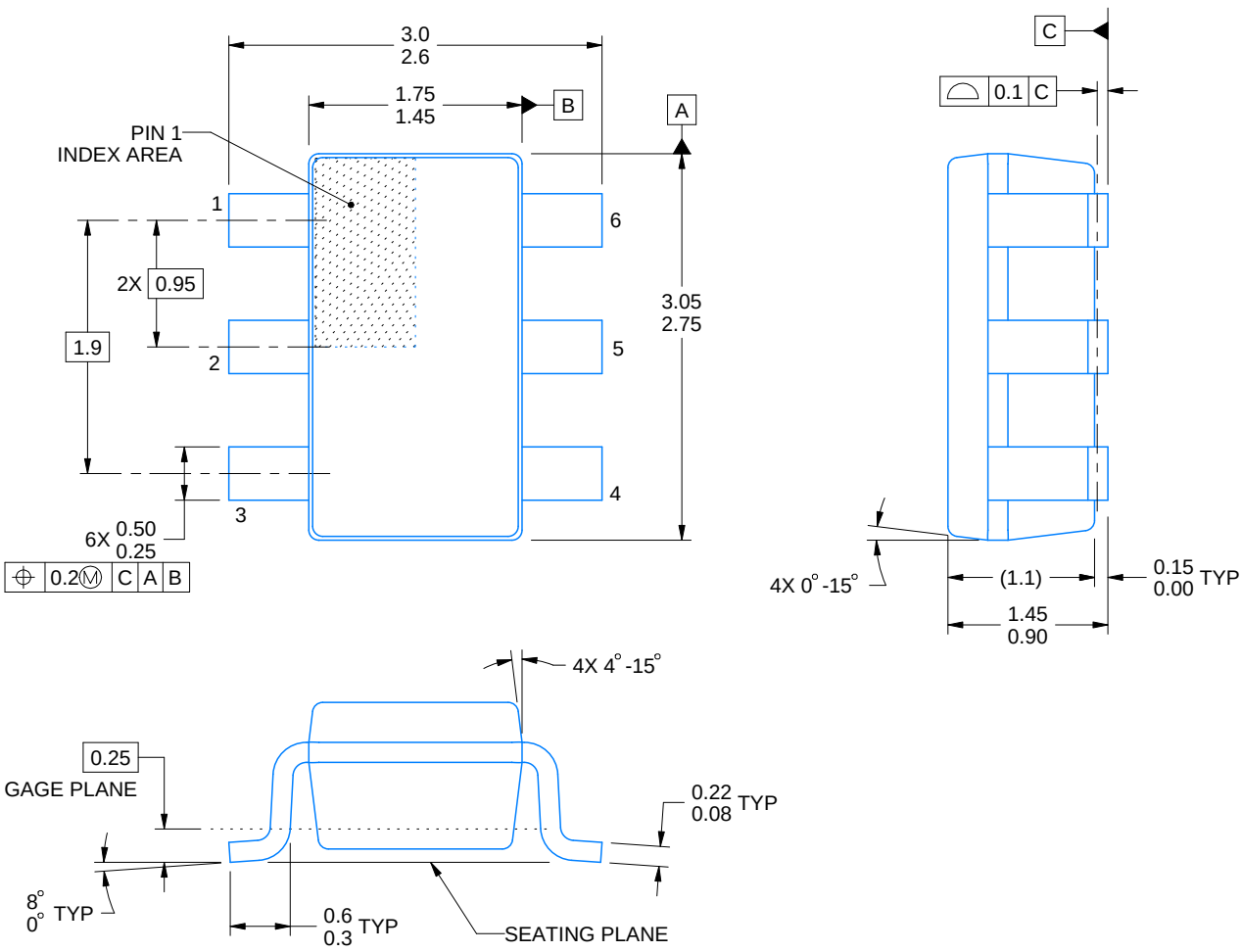
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

DBV0006A

SOT-23 - 1.45 mm max height

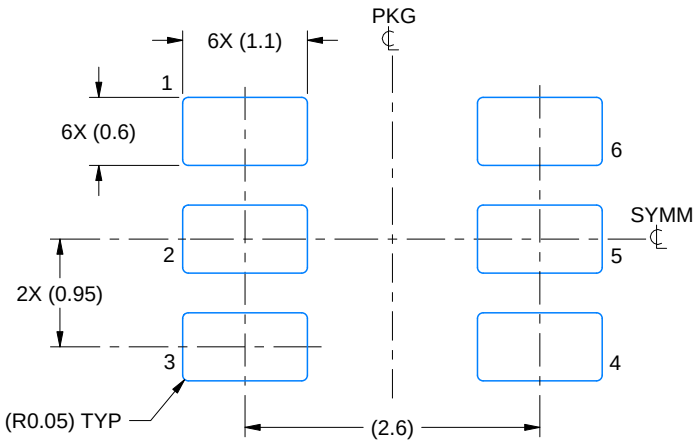
SMALL OUTLINE TRANSISTOR



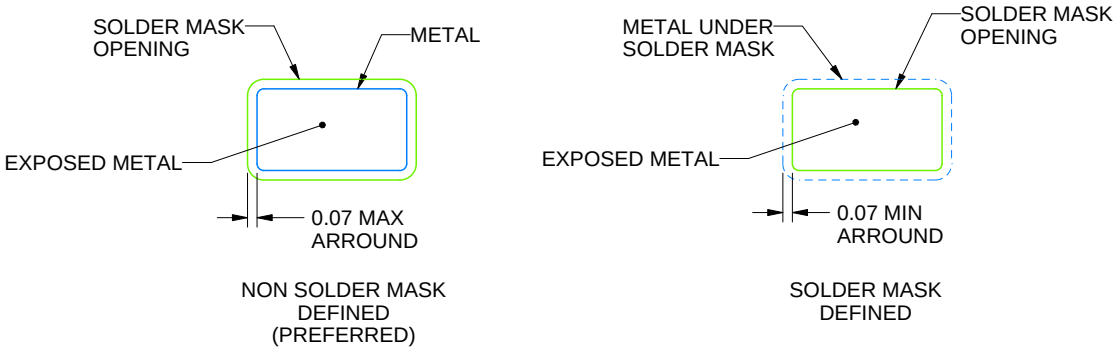
4214840/G 08/2024

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.25 per side.
4. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
5. Refernce JEDEC MO-178.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X

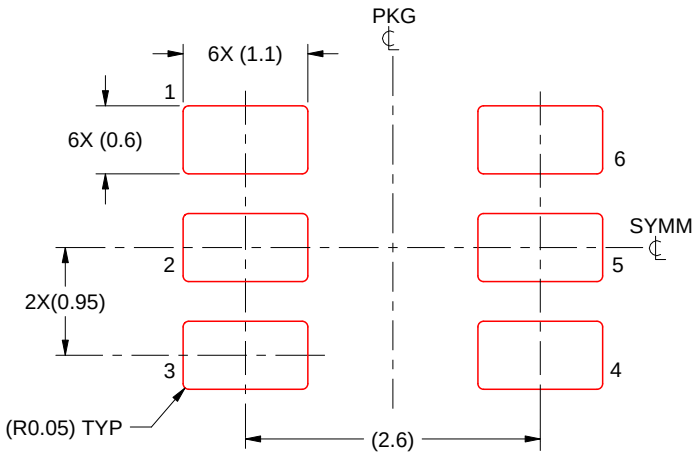


SOLDER MASK DETAILS

4214840/G 08/2024

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214840/G 08/2024

NOTES: (continued)

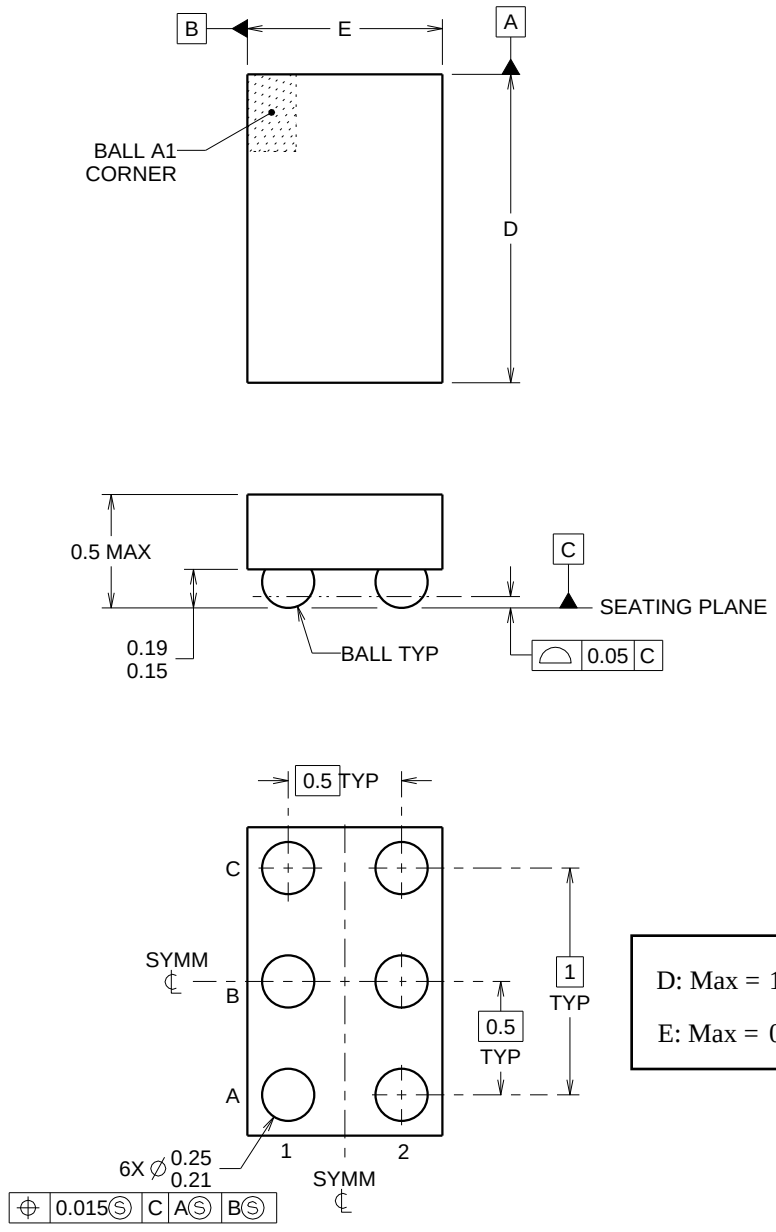
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

YZP0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



D: Max = 1.418 mm, Min =1.358 mm

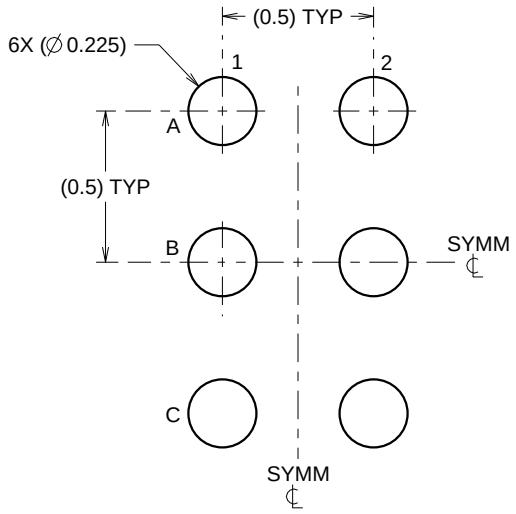
E: Max = 0.918 mm, Min =0.858 mm

4219524/A 06/2014

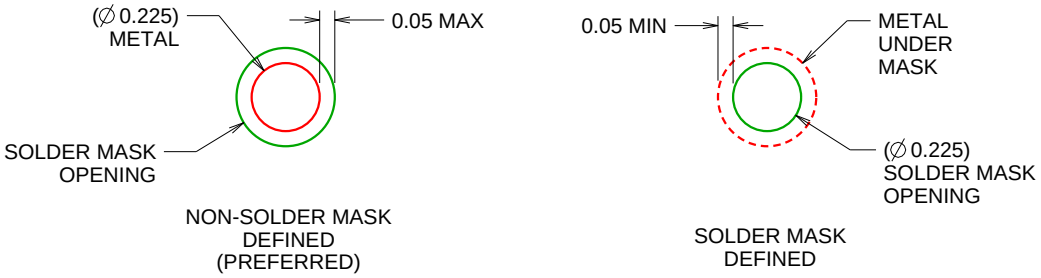
NOTES:

NanoFree Is a trademark of Texas Instruments.

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. NanoFree™ package configuration.



LAND PATTERN EXAMPLE
SCALE:40X

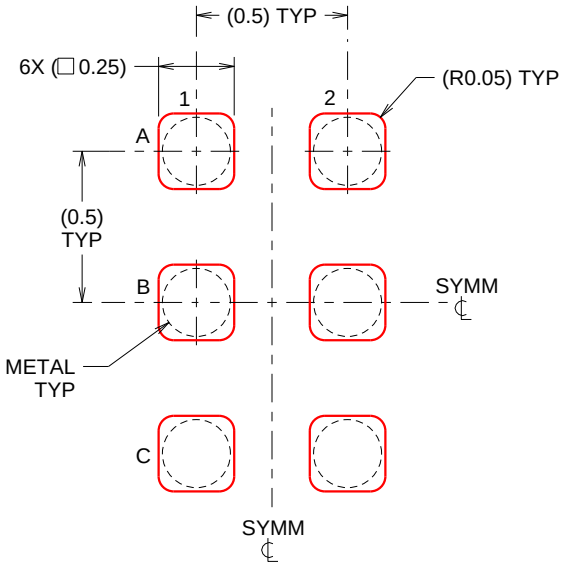


SOLDER MASK DETAILS
NOT TO SCALE

4219524/A 06/2014

NOTES: (continued)

4. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SBVA017 (www.ti.com/lit/sbva017).



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:40X

4219524/A 06/2014

NOTES: (continued)

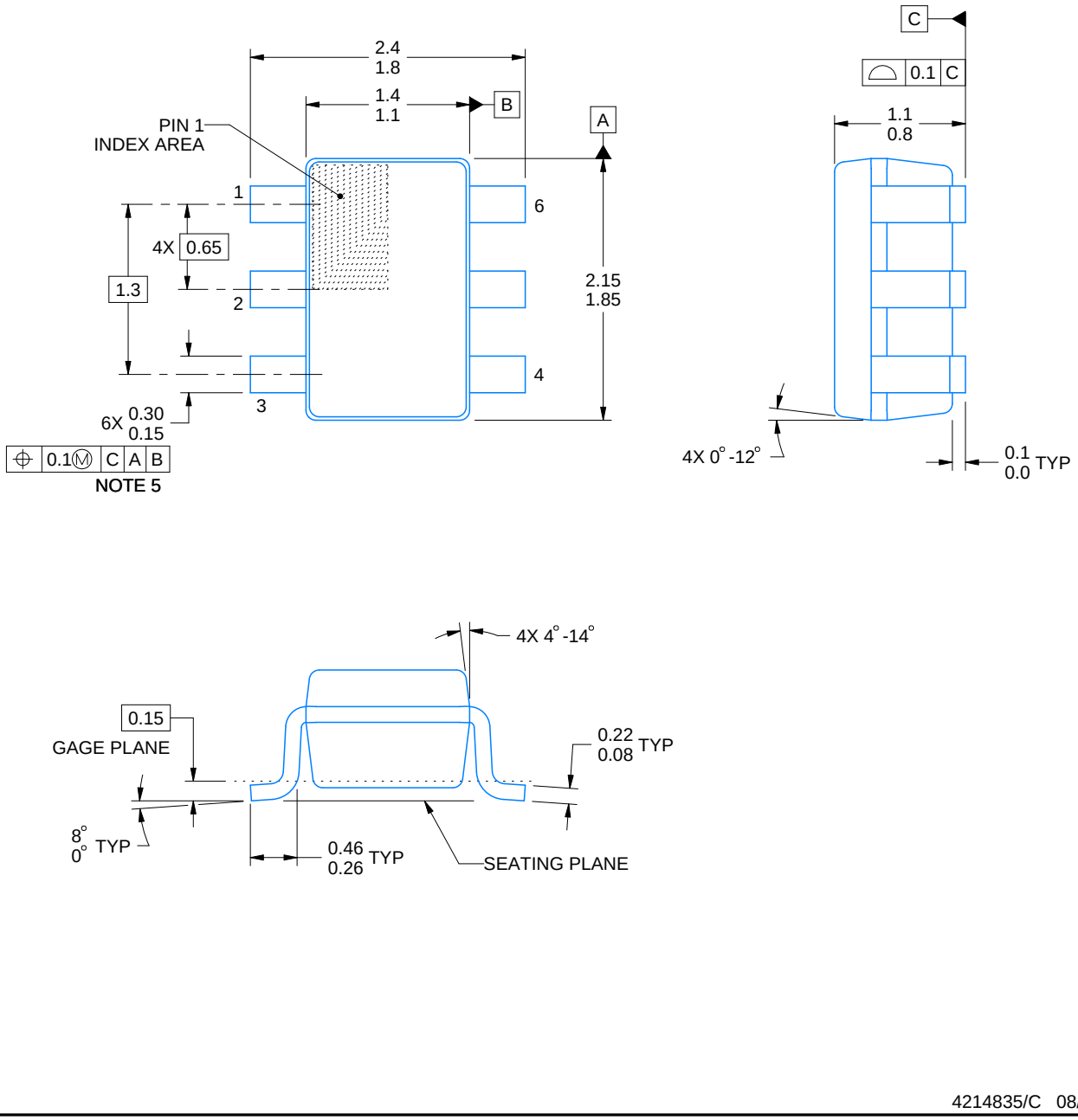
5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

PACKAGE OUTLINE

DCK0006A

SOT - 1.1 max height

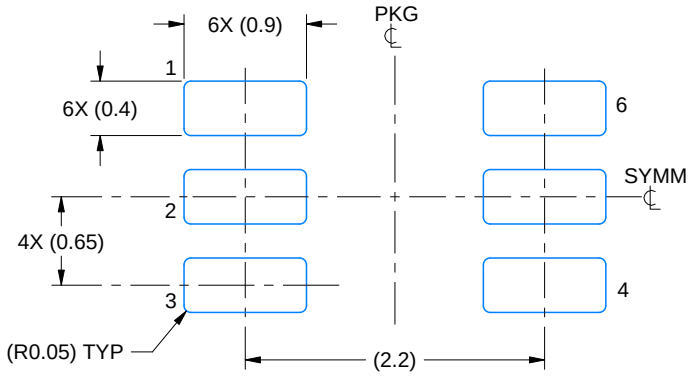
SMALL OUTLINE TRANSISTOR



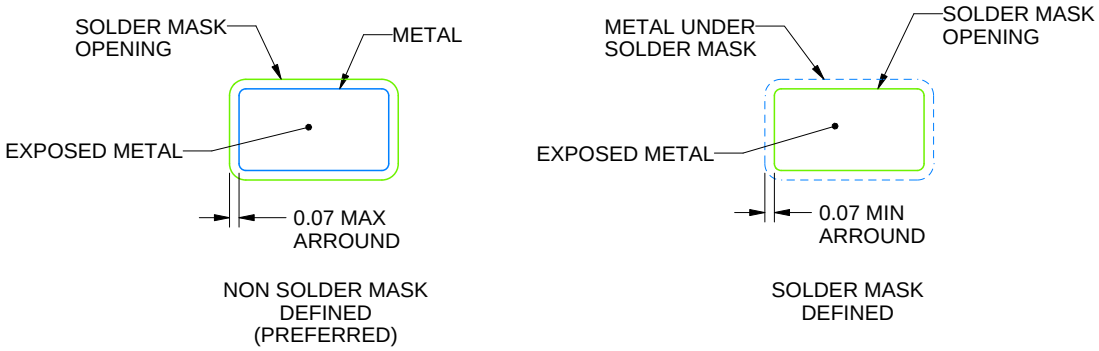
4214835/C 08/2024

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
4. Falls within JEDEC MO-203 variation AB.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X

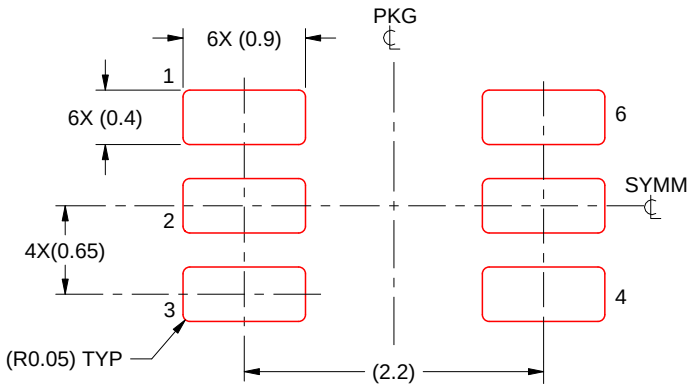


SOLDER MASK DETAILS

4214835/C 08/2024

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:18X

4214835/C 08/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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